

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

- 1 1. (Currently amended) A method of managing surface images of thin-film
2 devices comprising the steps of:
3 picking up at least one die region on a wafer surface by image pickup means to
4 produce the whole image of said region; ~~and~~
5 storing data of said whole image in memory means so that said data can be output
6 from said memory means[.];
7 8 inspection means or by a measuring means; and
9 displaying on a display screen said whole image of said region and said inputted
10 information of said region, including adjusting a magnification of said whole image to produce
11 an adjusted whole image and overlaying said adjusted whole image with said inputted
12 information of said region.
- 1 2. (Original) A method according to claim 1, wherein said image pickup means
2 is a two-dimensional imaging device, and said step of picking up includes picking up at least the
3 whole one-die region at a time by said two-dimensional imaging device.
- 1 3. (Original) A method according to claim 1, wherein said image pickup means
2 is a two-dimensional imaging device, and said step of picking up includes picking up a plurality
3 of portions of said one die region separately by said two-dimensional imaging device, and
4 composing the resulting partial images to produce said whole image.

1 4. (Original) A method according to claim 1, wherein said image pickup means
2 is a one-dimensional imaging device, and said step of picking up includes picking up a plurality
3 of portions of said one die region separately by said one-dimensional imaging device, and
4 composing the resulting partial images to produce said whole image.

1 5. (Original) A method according to claim 1, further comprising the steps of:
2 picking up a desired portion of said one die region to produce a detailed image of
3 said desired portion; and
4 displaying said detailed image and said whole image together by display means so
5 that these images can be observed at a time.

1 6. (Original) A method according to claim 5, wherein said detailed image and
2 said whole image are magnified or reduced at a desired magnifying power so that they can be
3 displayed in a magnified or reduced form.

1 7. (Currently amended) A method according to claim 1, wherein said
2 information of said region is particle information obtained by a particle inspection means
3 ~~separately without using said step of picking up can be output together with said whole image.~~

1 8. (Currently amended) A method according to claim 1, wherein said
2 information of said region is film thickness information obtained ~~separately without using said~~
3 ~~step of picking up can be output together with said whole image~~ by a film thickness measuring
4 means.

1 9. (Currently amended) A method according to claim [1]5, wherein said whole
2 image or said ~~partial~~ detailed image is subjected to image processing so that the image obtained
3 by said processing can be output.

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2 10. (Original) A method according to claim 9, wherein said image processing
3 extracts a proposed region of film thickness measurement point.

1 11. (Original) A method according to claim 9, wherein said image processing
2 detects a film thickness distribution.

1 12. (Original) A method according to claim 1, wherein desired information is
2 extracted by comparing said whole image and design information.

1 13. (Currently amended) A method according to claim 1, wherein said whole
2 image stored in said memory means is searched for under a ~~proper~~plurality of search conditions,
3 and the result of said searching can be output.

1 14. (Currently amended) A managing apparatus for surface image of thin-film
2 device comprising:

3 image pickup means for picking up at least one die region on a wafer surface; and
4 memory means for storing data of a whole image of said region picked up by said
5 image pickup means[.];

6 examination means for producing examination information for at least a portion
7 of said region, said examination information comprising inspection information or measurement
8 information;

9 display means for displaying an image comprising said whole image overlaid with
10 said examination information.

1 15. (Currently amended) A managing apparatus according to claim 14, wherein
2 said display means further includes adjusting a magnification of said whole image. ~~further~~
3 ~~comprising:~~

4 ~~displaying means for displaying said whole image stored in said memory means.~~

 16. (Original) A managing apparatus according to claim 15, further comprising:
 image pickup means for picking up a desired portion of said one die region to
produced a detailed image of said portion, wherein said display means displays said detailed
image and said whole image together.

1 17. (Currently amended) A management system for surface image of thin-film
2 device comprising:
3 image pickup means for picking up at least one die region on a wafer surface;
4 examination means for producing examination information for at least a portion
5 of said region, said examination information comprising inspection information or measurement
6 information;
7 memory means for storing data of a whole image of said region picked up by said
8 image pickup means; and
9 a plurality of display means for displaying said whole image stored in said
10 memory means, these display means being connected to said memory means through lines of
11 communication[.],
12 at least one of said display means operative to display said whole image overlaid
13 with said examination information.

1 18. (Currently amended) A method of manufacturing thin-film devices
2 comprising ~~the~~ steps of:
3 picking up at least one die region on a wafer surface by image pickup means to
4 produce a whole image of said region;
5 storing data of said whole image in memory means so that said data can be output
6 from said memory means; and
7 obtaining inspection information for said one die region from an inspection
8 apparatus or from a measurement apparatus;
9 picking up a desired portion of said one die region to produce a detailed image of
10 said portion, said detailed image and said whole image being used to decide if the dies formed on
11 said wafer are nondefective or defective[.]; and
12 displaying a magnified portion of said whole image overlaid with said inspection
13 information.

1 19. (Original) A manufacturing method according to claim 18, wherein defect
2 tendency is extracted on the basis of said whole image.

1 20. (Currently amended) An apparatus for producing thin-film devices
2 comprising:

3 image pickup means for picking up at least one die region on a wafer surface to
4 produce a whole image of said region;

5 memory means for storing data of said whole image; ~~and~~

6 test apparatus for producing inspection information or measurement information
7 for said die region;

8 image pickup means for picking up a desired portion of said one die region to
9 produce a detailed image of said portion, said detailed image and said whole image being used to
10 device if the dies formed on said wafer surface are nondefective or defective[.]; and

11 display means for displaying a magnified portion of said whole image overlaid
12 with said inspection information or measurement information.